

SuperFETTM

FCA47N60F 600V N-Channel MOSFET, FRFET

Features

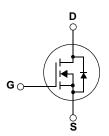
- 650V @T_J = 150°C
- Typ. $R_{DS(on)} = 0.062\Omega$
- Fast Recovery Type (t_{rr} = 240ns)
- Ultra Low Gate Charge (typ. Q_q = 210nC)
- Low Effective Output Capacitance (typ. C_{oss}eff. = 420pF)
- 100% avalanche tested

Description

SuperFETTM is, Fairchild's proprietary, new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance.

This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, SuperFET is very suitable for various AC/DC power conversion in switching mode operation for system miniaturization and higher efficiency.





Absolute Maximum Ratings

Symbol	Parameter			FCA47N60F	Unit	
V _{DSS}	Drain-Source Voltage			600	V	
I _D	Drain Current - Continuous (T _C = 25°C) - Continuous (T _C = 100°C)			47 29.7	A A	
I _{DM}	Drain Current	- Pulsed	(Note 1)	141	А	
V _{GSS}	Gate-Source voltage			± 30	V	
E _{AS}	Single Pulsed Avalanche Energy		(Note 2)	1800	mJ	
I _{AR}	Avalanche Current		(Note 1)	47	А	
E _{AR}	Repetitive Avalanche Energy		(Note 1)	41.7	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note		(Note 3)	50	V/ns	
P_D	Power Dissipation	(T _C = 25°C) - Derate above 25°C		417 3.33	W W/°C	
T _{J,} T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C	
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		9,	300	°C	

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.3	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		41.7	°C/W

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCA47N60F	FCA47N60F	TO-3PN	=	=	30

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Off Charac	teristics				ı	
BV _{DSS}	Drain-Source Breakdown Voltage	age $V_{GS} = 0V, I_D = 250\mu A, T_J = 25^{\circ}C$				V
		$V_{GS} = 0V, I_D = 250\mu A, T_J = 150^{\circ}C$		650		V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C		0.6		V/°C
BV _{DS}	Drain-Source Avalanche Breakdown Voltage	$V_{GS} = 0V$, $I_D = 47A$		700		V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 600V, V _{GS} = 0V V _{DS} = 480V, T _C = 125°C			10 100	μ Α μ Α
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V$, $V_{DS} = 0V$			-100	nA
On Charac	teristics				•	
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 23.5A		0.062	0.073	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40V, I _D = 23.5A (Note 4)		40		S
Dynamic C	Characteristics				•	
C _{iss}	Input Capacitance $V_{DS} = 25V, V_{GS} = 0V,$			5900	8000	pF
C _{oss}	Output Capacitance	f = 1.0MHz		3200	4200	pF
C _{rss}	Reverse Transfer Capacitance			250		pF
C _{oss}	Output Capacitance	V _{DS} = 480V, V _{GS} = 0V, f = 1.0MHz		160		pF
Coss eff.	Effective Output Capacitance	$V_{DS} = 0V$ to 400V, $V_{GS} = 0V$		420		pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 300V, I_{D} = 47A$		185	430	ns
t _r	Turn-On Rise Time	$R_G = 25\Omega$		210	450	ns
t _{d(off)}	Turn-Off Delay Time			520	1100	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		75	160	ns
Qg	Total Gate Charge	V _{DS} = 480V, I _D = 47A		210	270	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10V		38		nC
Q_{gd}	Gate-Drain Charge	(Note 4, 5)		110		nC
Drain-Sour	rce Diode Characteristics and Maximur	n Ratings			•	
I _S	Maximum Continuous Drain-Source Dio	de Forward Current			47	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F	orward Current			141	Α
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 47A			1.4	٧
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 47A		240		ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$ (Note 4)		2.04		μС

NOTES:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I_{AS} = 18A, V_{DD} = 50V, R_{G} = 25 $\!\Omega$, Starting T_{J} = 25 $\!^{\circ}C$
- 3. I_{SD} \leq 47A, di/dt \leq 1,200A/ $\mu s,~V_{DD} \leq$ BV $_{DSS},~Starting~T_J$ = $25^{\circ}C$
- 4. Pulse Test: Pulse width $\leq 300 \mu \text{s}, \, \text{Duty Cycle} \leq 2\%$
- 5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

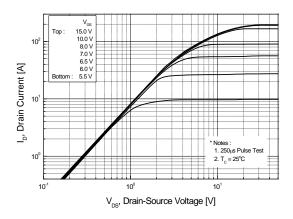


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

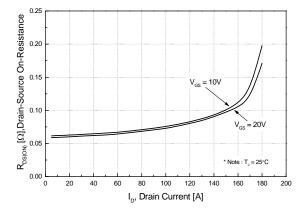


Figure 2. Transfer Characteristics

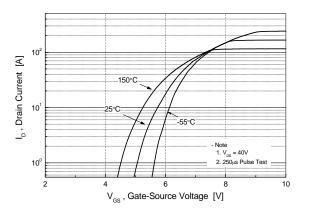


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

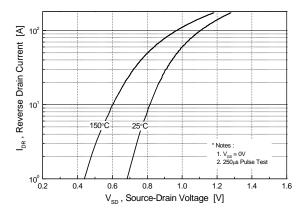


Figure 5. Capacitance Characteristics

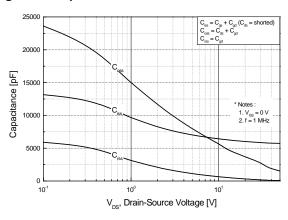
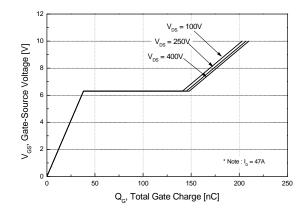


Figure 6. Gate Charge Characteristics



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Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

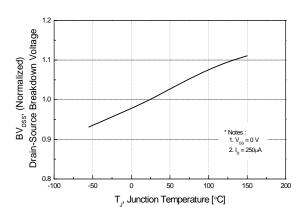


Figure 8. On-Resistance Variation vs. Temperature

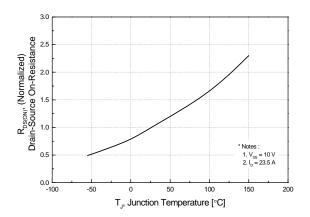


Figure 9. Safe Operating Area

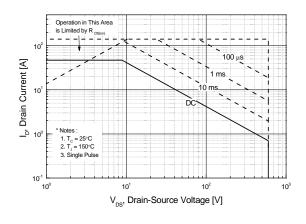


Figure 10. Maximum Drain Current vs. Case Temperature

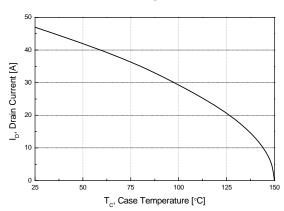
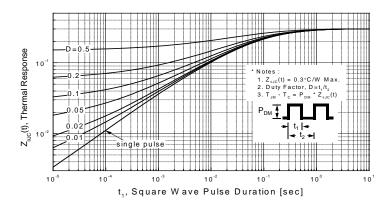
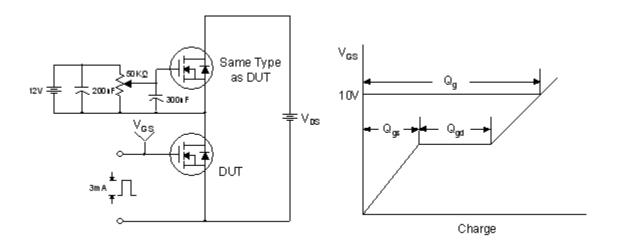


Figure 10. Transient Thermal Response Curve

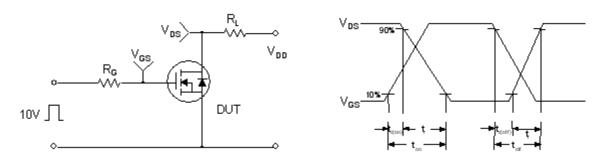


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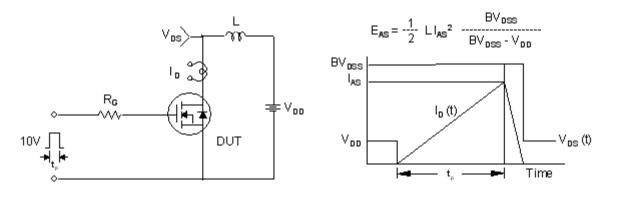
Gate Charge Test Circuit & Waveform



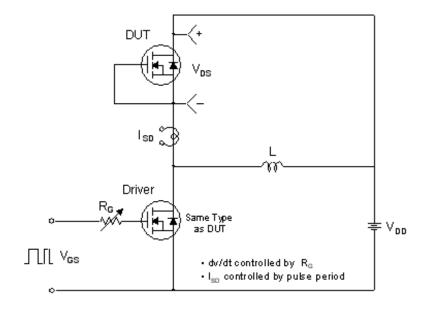
Resistive Switching Test Circuit & Waveforms

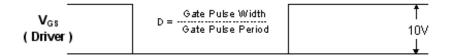


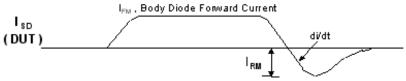
Unclamped Inductive Switching Test Circuit & Waveforms



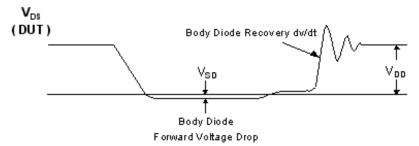
Peak Diode Recovery dv/dt Test Circuit & Waveforms







Body Diode Reverse Current



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